<b>PC</b> SECONTION CONNECTING CODYRIGHT 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
			Form Type Distribute					rials and M	ials and Mfg Information					
Supplier Information														
Company name* Compan			pany unique ID			Unique ID Authority				Respon	Response Date*			
onsemi											2024-05-18			
tontact Name Title - Contact			et		Phone - Contact*				Email -	Email - Contact*				
Product-Env-Stewards Product Env			wiro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Representative			esentative			Phone - Representative*				Email - Representative*				
Product-Env-Stewards Produ			Product Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Requester Item Number	Requester Item Number Mfr Iten		n Number Mfr Item Name			Effective Date Version Manufacturing Site		Ianufacturing Site		Weight*	UOM	Unit Type		
	FDN358	FDN358P 30V P-FET 125 MC		MO SSOT3		2024-05-18		M	MY1		10.57	mg	Each	
Aanufacturing Proccess Informa	ation													
Terminal Plating / Grid Array M	Iaterial 7	rial Terminal Base Alloy		J-STD-020 MSL	20 MSL Rating Pe		eak Process Body Temperature Max Time at Peal		k Tempera	ture Num	nber of Reflow Cyc	eles		
Matte Tin (Sn) - annealed CU Alloy		CU Alloy	1			<b>260</b> C		С	30 seco		seconds 3			
omments														
vel 1 - maximum time at peak temperat	ture during so	ldering is 10-3	0 seconds											
or more information regarding materia	l composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth					
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of				
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted					
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.									
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the				
Supplier Digital Signature Ra	stislav Drska	Le							

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

sigma range of distribution unless otherwise noted).									
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure	
Die	0.766	mg	Supplier	Silicon (Si)	7440-21-3		0.766	mg	
Lead Frame	3.699	mg	Supplier	Silver (Ag)	7440-22-4		0.015	mg	
			Supplier	Zinc (Zn)	7440-66-6		0.005	mg	
			Supplier	Iron (Fe)	7439-89-6		0.088	mg	
			Supplier	Copper (Cu)	7440-50-8		3.59	mg	
			Supplier	Phosphorus (P)	7723-14-0		0.001	mg	
Mold Compound-Black	5.697	mg		Epoxy resin	proprietary data		0.2849	mg	
			Supplier	Phenolic Resin	Proprietary Data		0.2849	mg	
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.1139	mg	
			Supplier	Carbon Black (C)	1333-86-4		0.0285	mg	
			Supplier	Fused Silica (SiO2)	60676-86-0		4.9849	mg	
Plating	0.332	mg	Supplier	Tin (Sn)	7440-31-5		0.332	mg	
Wire Bond - Au	0.076	mg	Supplier	Gold (Au)	7440-57-5		0.076	mg	